

# 2SK2008

### Silicon N Channel MOS FET

REJ03G0992-0200

(Previous: ADE-208-1340)

Rev.2.00 Sep 07, 2005

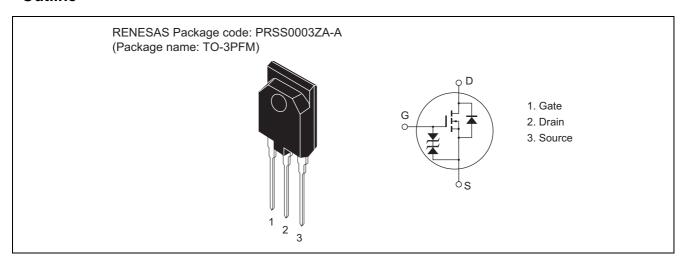
#### **Application**

High speed power switching

#### **Features**

- Low on-resistance
- High speed switching
- Low drive current
- No Secondary Breakdown
- Suitable for Switching regulator, DC DC converter, motor control

#### **Outline**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	250	V
Gate to source voltage	$V_{GSS}$	±30	V
Drain current	I <sub>D</sub>	20	А
Drain peak current	I <sub>D(pulse)</sub> *1	80	А
Body to drain diode reverse drain current	I <sub>DR</sub>	20	А
Channel dissipation	Pch*2	60	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1 %

2. Value at Tc = 25°C

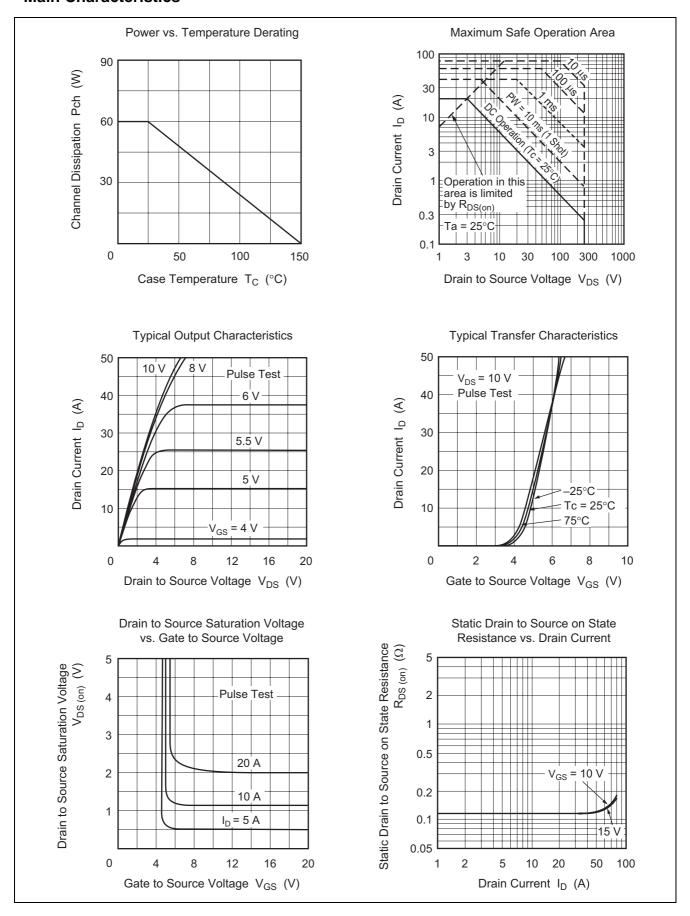
### **Electrical Characteristics**

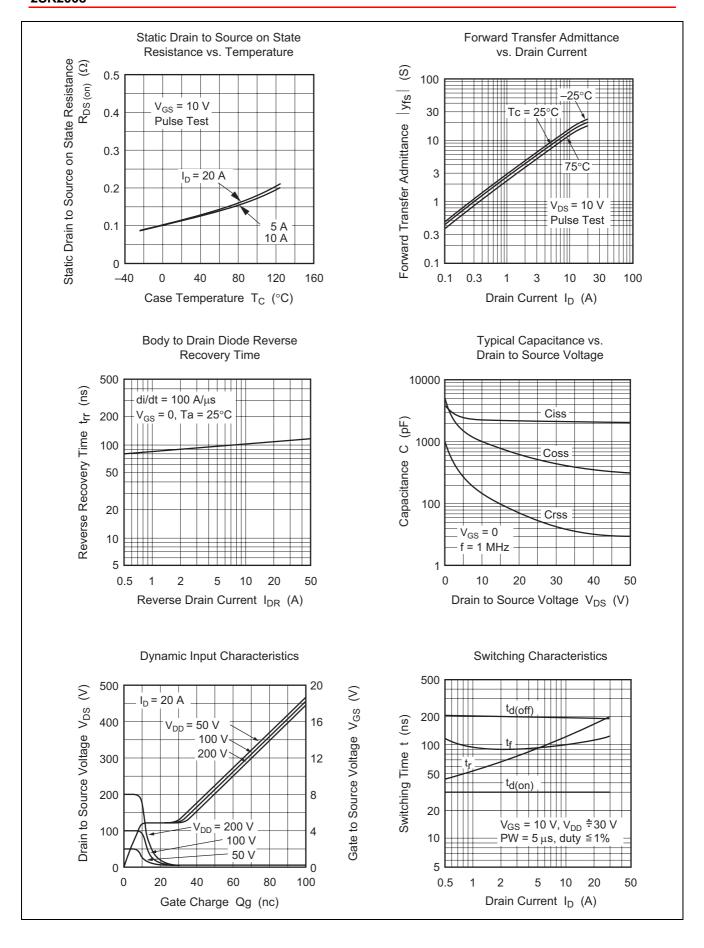
 $(Ta = 25^{\circ}C)$ 

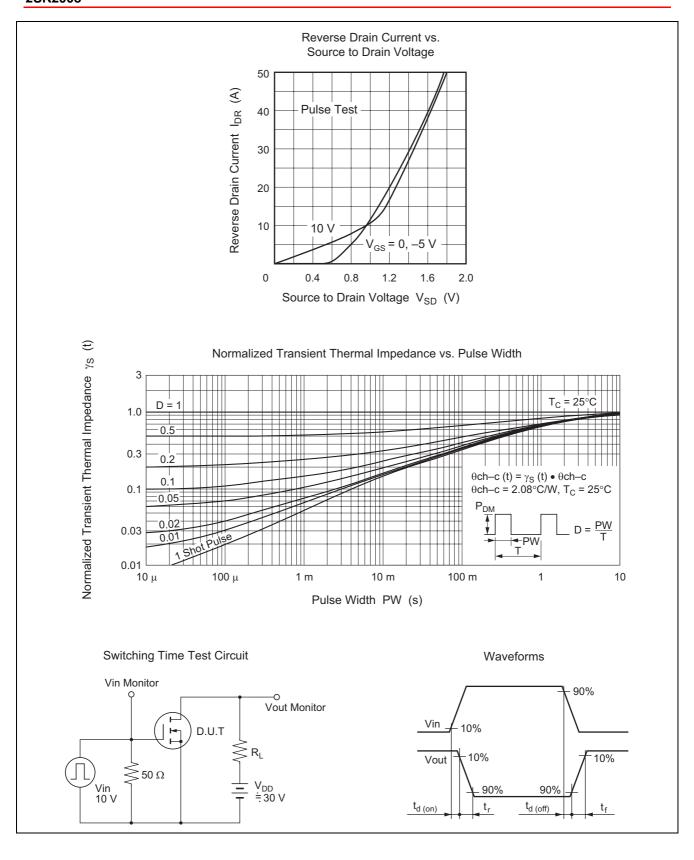
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V <sub>(BR)DSS</sub>	250	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	250	μΑ	$V_{DS} = 200 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V <sub>GS(off)</sub>	2.0	_	3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state	R <sub>DS(on)</sub>	_	0.12	0.15	Ω	$I_D = 10 \text{ A}, V_{GS} = 10 \text{ V}^{*3}$
resistance						
Forward transfer admittance	y <sub>fs</sub>	9.0	14		S	$I_D = 10 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$
Input capacitance	Ciss	_	2340	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	1000	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	160	_	pF	
Turn-on delay time	t <sub>d(on)</sub>	_	30	_	ns	$I_D = 10 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t <sub>r</sub>	_	125	_	ns	$R_L = 3 \Omega$
Turn-off delay time	$t_{d(off)}$	_	190	_	ns	
Fall time	t <sub>f</sub>	_	100	_	ns	
Body to drain diode forward voltage	$V_{DF}$	_	1.2	_	V	$I_F = 20 \text{ A}, V_{GS} = 0$
Body to drain diode reverse	t <sub>rr</sub>	_	120	_	ns	$I_F = 20 \text{ A}, V_{GS} = 0,$
recovery time						$di_{F} / dt = 100 A / \mu s$

Note: 3. Pulse Test

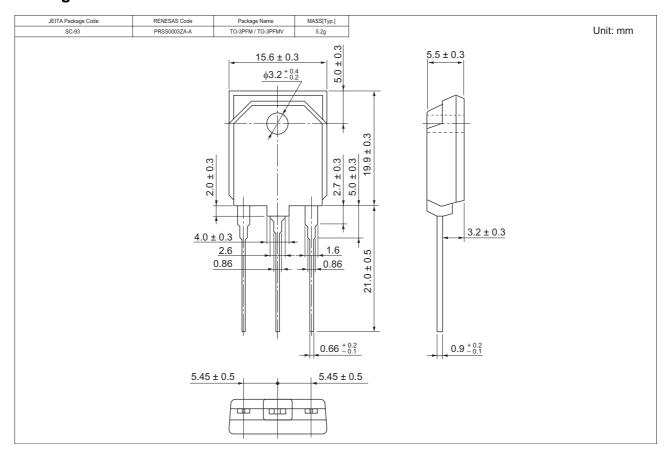
#### **Main Characteristics**







## **Package Dimensions**



### **Ordering Information**

Part Name	Quantity	Shipping Container
2SK2008-E	360 pcs	Box (Tube)

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